

XYZTEC

Company profile

XYZTEC is a global technology and innovation leader in advanced bond testing and material testing solutions for the electronics and semiconductor industries. With worldwide sales, application expertise, and technical support, XYZTEC provides high-precision testing technologies to leading manufacturers, research institutions, and technology companies around the world.

XYZTEC's systems support the development, qualification, production, and reliability assurance of critical electronic components and interconnection technologies across a broad range of industries, including **semiconductors, consumer electronics, automotive, medical devices, aerospace, defense, telecommunications, and advanced research.**

As an innovation-driven technology provider, XYZTEC develops advanced testing solutions that enable customers to evaluate product quality and long-term reliability, optimize manufacturing processes, and accelerate the introduction of new technologies. XYZTEC equipment is used by many of the world's leading manufacturers and technology organizations throughout their R&D, quality assurance, and production environments.

The XYZTEC Sigma bond tester machines (Sigma, Sigma Lite, Sigma W8, Sigma W12, Sigma MAG and Sigma HF) conform, and in many cases exceed, the following industry standards regarding the performance of bond tests:

Test type	Corresponding standard
Au ball shear	JEDEC JESD22-B116
Ball bond shear	ASTM F1269
BGA ball shear	JEDEC JESD22-B117A
Cold bump pull	JEDEC JESD22-B115
Cold bump pull & hot bump pull	JEITA EIAJ ET-7407, IPC-9708
Die shear	MIL STD 883
Flip chip pull	JEDEC JESD22-B109
Inline wire pull test (non-destructive)	DVS 2811
Tweezer / peel test	DVS 2811
Stud pull	MIL STD 883
Wedge shear test	DVS 2811
Wire pull	DT/NDT MIL STD 883, DVS 2811
Wire bonded joints in general	DVS 2811



Make sure your products meet the highest quality standards too.